

Description

The AP160N04P/T uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 40V I_D =160 A

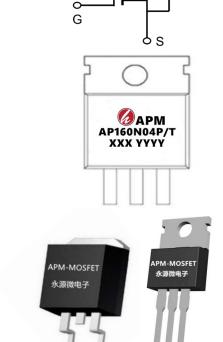
 $R_{DS(ON)}$ < 3.0m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

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Product ID	Pack	Marking	Qty(PCS)
AP160N04P	TO-220-3L	AP160N04P XXX YYYY	1000
AP160N04T	TO-263-3L	AP160N04T XXX YYYY	1000

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

		-	1
Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	40	V
V _G s	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	160	Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	142	А
Ідм	Pulsed Drain Current ²	400	А
EAS	Single Pulse Avalanche Energy ³	400	mJ
las	Avalanche Current	40	Α
P _D @T _C =25°C	Total Power Dissipation ⁴	178	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
$R_{ heta}$ JA	Thermal Resistance Junction-Ambient ¹	50	°C/W
Rejc	Thermal Resistance Junction-Case ¹	0.7	°C/W



AP160N04P/T

40V N-Channel Enhancement Mode MOSFET

Electrical Characteristics (T_J=25℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40			V
RDS(ON)	ON) Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =20A		1.9	3.0	mΩ
(011)	Otatic Brain-Oddrec On-Nesistance	V _{GS} =4.5V , I _D =20A		2.3	3.5	11152
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.2	1.6	2.2	V
IDSS	Drain-Source Leakage Current	V _{DS} =32V , V _{GS} =0V , T _J =25℃			1	uA
	Drain Godieo Zoditago Garront	V_{DS} =32 V , V_{GS} =0 V , T_{J} =55 $^{\circ}$ C			5	
IGSS	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =20A		53		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.0		Ω
Qg	Total Gate Charge (4.5V)			45		
Qgs	Gate-Source Charge	V _{DS} =15V , V _{GS} =10V , I _D =20A		12		nC
Qgd	Gate-Drain Charge			18.5		
Td(on)	Turn-On Delay Time			18.5		
Tr	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω ,		9		
Td(off)	Turn-Off Delay Time	I _D =20A		58.5		ns
T _f	Fall Time			32		
Ciss	Input Capacitance			3972		
Coss	Output Capacitance	V _{DS} =20V , V _{GS} =0V , f=1MHz		1119		pF
Crss	Reverse Transfer Capacitance			82		
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			150	Α
Vsp	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25℃			1.2	V

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width $\, \leqq \,$ 300us , duty cycle $\, \leqq \,$ 2%
- $3\sqrt{100}$ The EAS data shows Max. rating . The test condition is V DD =25V,V GS =10V,L=0.5mH,I AS =40A
- 4. The power dissipation is limited by 150℃ junction temperature
- 5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.
- 6. Package limitation current is 180A



Typical Characteristics

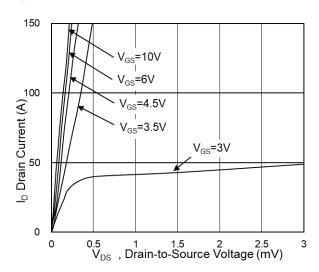


Fig.1 Typical Output Characteristics

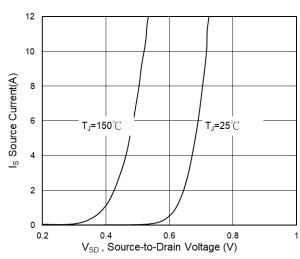


Fig.3 Source Drain Forward Characteristics

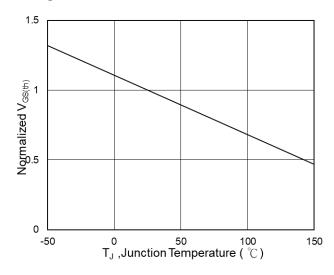


Fig.5 Normalized $V_{\text{GS(th)}}$ vs T_{J}

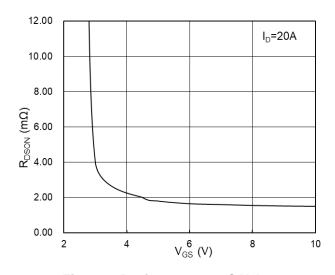


Fig.2 On-Resistance vs G-S Voltage

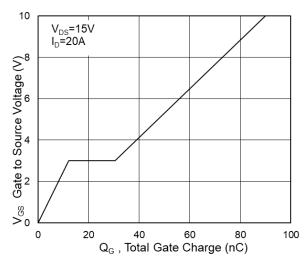


Fig.4 Gate-Charge Characteristics

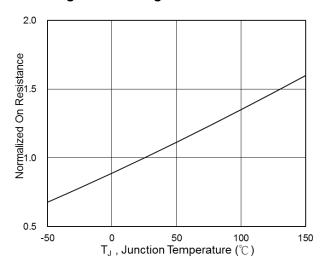
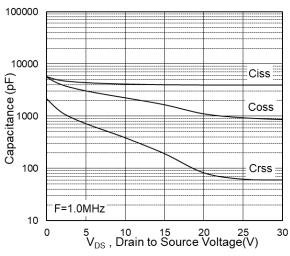


Fig.6 Normalized RDSON vs TJ



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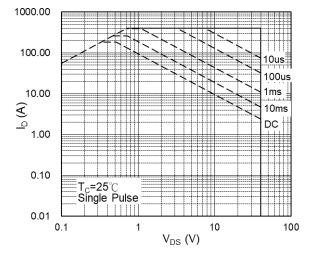


Fig.7 Capacitance

Fig.8 Safe Operating Area

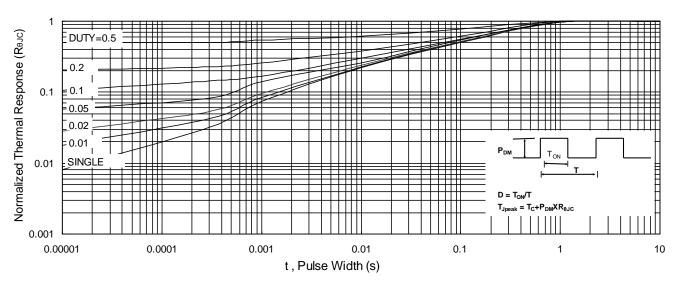


Fig.9 Normalized Maximum Transient Thermal Impedance

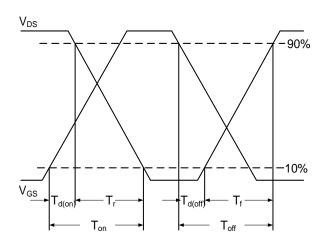
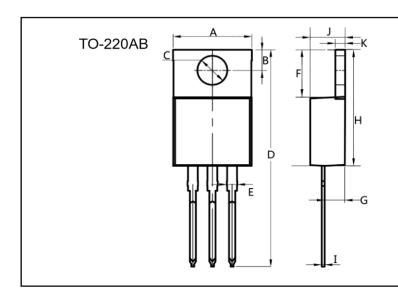


Fig.10 Switching Time Waveform

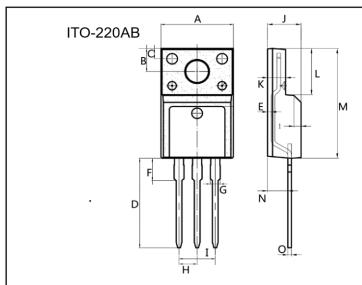
Fig.11 Unclamped Inductive Switching Waveform



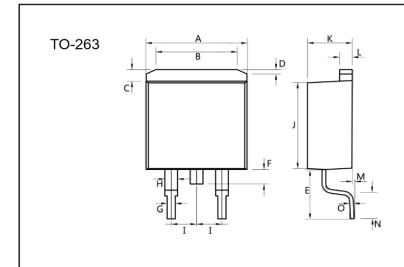




Dim.	Min.	Max.
Α	10.0	10.4
В	2.5	3.0
С	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
Н	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4
All Dimensions in millimeter		



Dim.	Min.	Max.	
Α	9.9	10.3	
В	2.9	3.5	
С	1.15	1.45	
D	12.75	13.25	
E	0.55	0.75	
F	3.1	3.5	
G	1.25	1.45	
Н	Typ 2.54		
I	Typ 5.08		
J	4.55	4.75	
K	2.4	2. 7	
L	6.35	6.75	
М	15.0	16.0	
N	2.75	3.15	
0	0.45	0.60	
All Dimensions in millimeter			



DIM.	IVIIN.	wax.	
Α	10.0	10. 5	
В	7.25	7.75	
С	1.3	1.5	
D	0.55	0.75	
E	5.0	6.0	
F	1.4	1.6	
G	0.75	0.95	
Н	1.15	1.35	
	Typ 2.54		
I	Тур	2.54	
J	Тур 8.4	2.54 8.6	
J	8.4	8.6	
J K	8.4 4.4	8.6 4.6	
J K L	8.4 4.4 1.25	8.6 4.6 1.45	
J K L	8.4 4.4 1.25 0.02	8.6 4.6 1.45 0.1	
J K L M N	8.4 4.4 1.25 0.02 2.4	8.6 4.6 1.45 0.1 2.8 0.45	





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Edition	Date	Change
Rve1.0	2020/4/1	Initial release

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